

REMARKS

Claims 1-18 and 20-27 are allowed; and claim 22 is rejected.

In response to the Examiner's rejection of claim 22 under 35 U.S.C. § 112, first paragraph, Applicants respectfully disagree with the Examiner's assertion that claim 22 introduces new matter into the specification.

Specifically, the limitation of "wherein said copper paste does not contain a glass frit" finds clear written description support at page 55, lines 12-14 (the copper paste of the present invention preferably contains no glass frit, because if contained, the plating property of the via conductor is impaired...) and at page 9, lines 1-4 (the reason why the copper paste of the first aspect can be suppressed from the protrusion of via conductor of a wiring board even if a glass frit is not contained is described below).

Also, the comparison of Comparative Examples 1-C and 1-D (containing glass frit) with Examples 1-C, 1-E and 1-F of the invention (no glass frit) further supports possession of the subject matter of claim 22 at the time the application was filed.

Withdrawal of all rejections and allowance of claims 1-18 and 20-27 is earnestly solicited.

In the event that the Examiner believes that it may be helpful to advance the prosecution of this application, the Examiner is invited to contact the undersigned at the local Washington, D.C. telephone number indicated below.

RESPONSE UNDER 37 C.F.R. § 1.116
U.S. Application No. 10/620,595

Q76617

The USPTO is directed and authorized to charge all required fees, except for the Issue Fee and the Publication Fee, to Deposit Account No. 19-4880. Please also credit any overpayments to said Deposit Account.

Respectfully submitted,



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